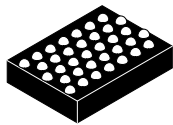


# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

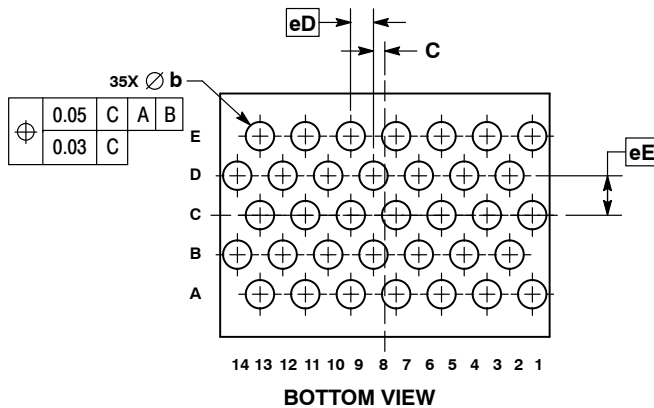
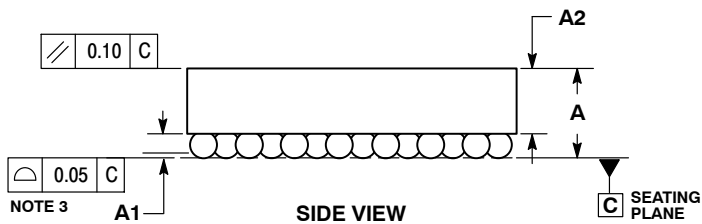
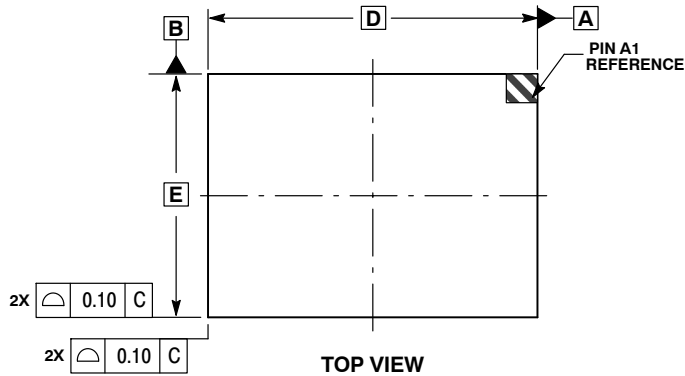
ON Semiconductor®



SCALE 4:1

WLCSP35, 3.63x2.68  
CASE 567AG-01  
ISSUE B

DATE 24 JAN 2011

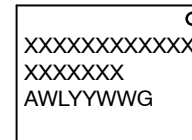


**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.84	1.00
A1	0.17	0.23
A2	0.72 REF	
b	0.24	0.29
C	0.125 BSC	
D	3.63 BSC	
E	2.68 BSC	
eD	0.25 BSC	
eE	0.433 BSC	

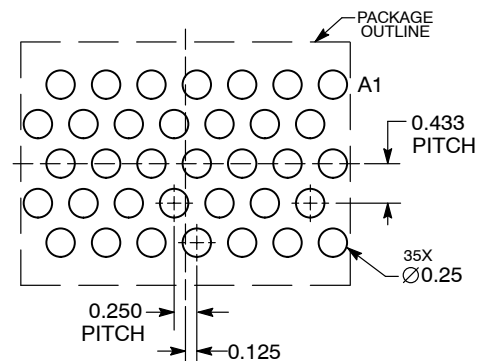
**GENERIC MARKING DIAGRAM\***



- XXXXXX = Device Code
- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking.

**RECOMMENDED SOLDERING FOOTPRINT\***



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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<b>REFERENCE:</b>		
<b>DESCRIPTION:</b>	WLCSP35, 3.63X2.68	<b>PAGE 1 OF 2</b>



ISSUE	REVISION	DATE
O	RELEASED FOR PRODUCTION FROM POD #08-0004 TO ON SEMICONDUCTOR. REQ. BY B. BERGMAN.	09 JUL 2008
A	REformatted DRAWING TO JEDEC STANDARDS. REQ. BY C. CALAME.	02 NOV 2010
B	REVERSED PACKAGE ORIENTATION. REQ. BY C. CALAME.	24 JAN 2011

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